

MC74AC273, MC74ACT273

Octal D Flip-Flop

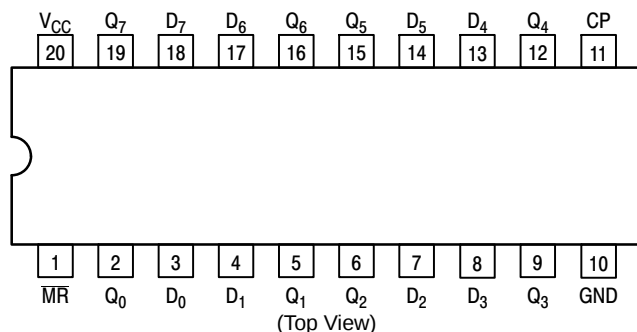
The MC74AC273/74ACT273 has eight edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset ($\overline{\text{MR}}$) inputs load and reset (clear) all flip-flops simultaneously.

The register is fully edge-triggered. The state of each D input, one setup time before the LOW-to-HIGH clock transition, is transferred to the corresponding flip-flop's Q output.

All outputs will be forced LOW independently of Clock or Data inputs by a LOW voltage level on the $\overline{\text{MR}}$ input. The device is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements.

Features

- Ideal Buffer for MOS Microprocessor or Memory
- Eight Edge-Triggered D Flip-Flops
- Buffered Common Clock
- Buffered, Asynchronous Master Reset
- See MC74AC377 for Clock Enable Version
- See MC74AC373 for Transparent Latch Version
- See MC74AC374 for 3-State Version
- Outputs Source/Sink 24 mA
- 'ACT273 Has TTL Compatible Inputs
- These are Pb-Free Devices



MODE SELECT-FUNCTION TABLE

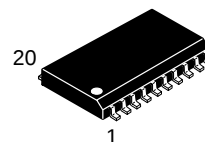
Operating Mode	Inputs			Outputs
	MR	CP	D _n	Q _n
Reset (Clear)	L	X	X	L
Load '1'	H	┐	H	H
Load '0'	H	┐	L	L

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
┐ = LOW-to-HIGH Clock Transition

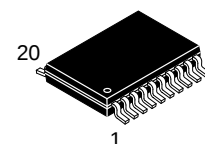


ON Semiconductor®

www.onsemi.com



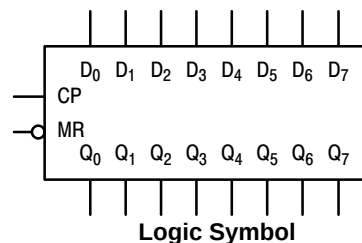
SOIC-20WB
SUFFIX DW
CASE 751D



TSSOP-20
SUFFIX DT
CASE 948E

PIN ASSIGNMENT

PIN	FUNCTION
D ₀ -D ₇	Data Inputs
$\overline{\text{MR}}$	Master Reset
CP	Clock Pulse Input
Q ₀ -Q ₇	Data Outputs



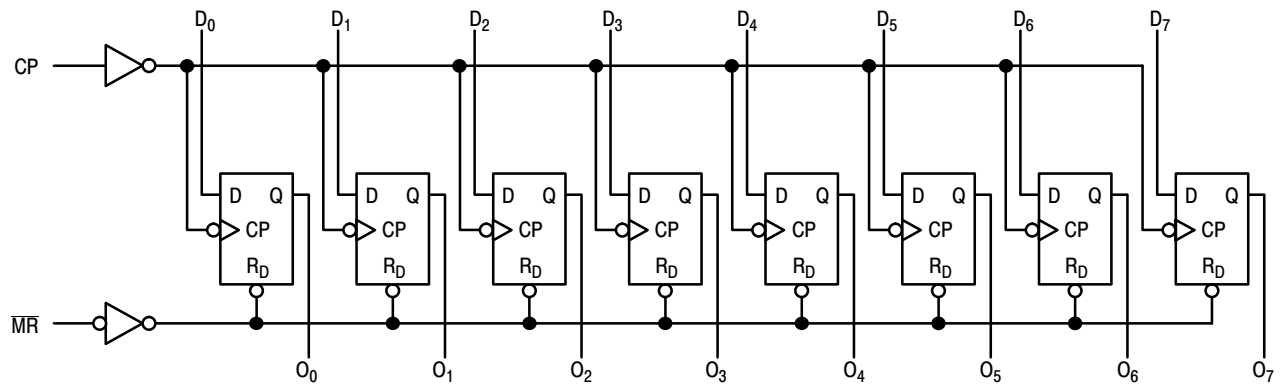
ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 6 of this data sheet.

MC74AC273, MC74ACT273



NOTE: That this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 1. Logic Diagram

MC74AC273, MC74ACT273

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V _{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V _{CC} +0.5	V
V _{OUT}	DC Output Voltage (Referenced to GND) (Note 1)	–0.5 to V _{CC} +0.5	V
I _{IK}	DC Input Diode Current	±20	mA
I _{OK}	DC Output Diode Current	±50	mA
I _{OUT}	DC Output Sink/Source Current	±50	mA
I _{CC}	DC Supply Current, per Output Pin	±50	mA
I _{GND}	DC Ground Current, per Output Pin	±100	mA
T _{STG}	Storage Temperature Range	– 65 to + 150	°C
T _L	Lead temperature, 1 mm from Case for 10 Seconds	260	°C
T _J	Junction Temperature Under Bias	140	°C
θ _{JA}	Thermal Resistance (Note 2)	SOIC TSSOP 65.8 110.7	°C/W
MSL	Moisture Sensitivity	SOIC TSSOP Level 3 Level 1	
F _R	Flammability Rating	Oxygen Index: 30% – 35%	UL 94 V–0 @ 0.125 in
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 > 1000
I _{Latchup}	Latchup Performance	Above V _{CC} and Below GND at 85°C (Note 6)	±100

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. I_{OUT} absolute maximum rating must be observed.
2. The package thermal impedance is calculated in accordance with JESD 51–7.
3. Tested to EIA/JESD22–A114–A.
4. Tested to EIA/JESD22–A115–A.
5. Tested to JESD22–C101–A.
6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit
V _{CC}	Supply Voltage	'AC	2.0	5.0	V
		'ACT	4.5	5.0	
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Ref. to GND)	0	–	V _{CC}	V
t _r , t _f	Input Rise and Fall Time (Note 7) 'AC Devices except Schmitt Inputs	V _{CC} @ 3.0 V	–	150	ns/V
		V _{CC} @ 4.5 V	–	40	
		V _{CC} @ 5.5 V	–	25	
t _r , t _f	Input Rise and Fall Time (Note 8) 'ACT Devices except Schmitt Inputs	V _{CC} @ 4.5 V	–	10	ns/V
		V _{CC} @ 5.5 V	–	8.0	
T _A	Operating Ambient Temperature Range	–40	25	85	°C
I _{OH}	Output Current – High	–	–	–24	mA
I _{OL}	Output Current – Low	–	–	24	mA

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

7. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
8. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

MC74AC273, MC74ACT273

DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74AC		74AC	Unit	Conditions
			T _A = +25°C		T _A = -40°C to +85°C		
			Typ	Guaranteed Limits			
V _{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
V _{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
V _{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I _{OUT} = -50 μA
		3.0 4.5 5.5	- - -	2.56 3.86 4.86	2.46 3.76 4.76	V	*V _{IN} = V _{IL} or V _{IH} -12 mA I _{OH} -24 mA -24 mA
V _{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I _{OUT} = 50 μA
		3.0 4.5 5.5	- - -	0.36 0.36 0.36	0.44 0.44 0.44	V	*V _{IN} = V _{IL} or V _{IH} 12 mA I _{OL} 24 mA 24 mA
I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μA	V _I = V _{CC} , GND
I _{OLD} I _{OHD}	†Minimum Dynamic Output Current	5.5 5.5	- -	- -	75 -75	mA	V _{OLD} = 1.65 V Max V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80	μA	V _{IN} = V _{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: Note: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V _{CC} * (V)	74AC			74AC		Unit	Figure No.
			T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF			
			Min	Typ	Max	Min	Max		
f _{max}	Maximum Clock Frequency	3.3 5.0	90 140	125 175	– –	75 125	– –	Mhz	3–3
t _{PLH}	Propagation Delay Clock to Output	3.3 5.0	4.0 3.0	7.0 5.5	12.5 9.0	3.0 2.5	14.0 10.0	ns	3–6
t _{PHL}	Propagation Delay Clock to Output	3.3 5.0	4.0 3.0	7.0 5.0	13.0 10.0	3.5 2.5	14.5 11.0	ns	3–6
t _{PHL}	Propagation Delay MR to Output	3.3 5.0	4.0 3.0	7.0 5.0	13.0 10.0	3.5 2.5	14.0 10.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V. Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V _{CC} * (V)	74AC		74AC		Unit	Figure No.
			T _A = +25°C C _L = 50 pF		T _A = -40°C to +85°C C _L = 50 pF			
			Typ	Guaranteed Minimum				
t _s	Setup Time, HIGH or LOW Data to CP	3.3 5.0	3.5 2.5	5.5 4.0	6.0 4.5	ns	3-9	
t _h	Hold Time, HIGH or LOW Data to CP	3.3 5.0	-2.0 -1.0	0 1.0	0 1.0	ns	3-9	
t _w	Clock Pulse Width HIGH or LOW	3.3 5.0	3.5 2.5	5.5 4.0	6.0 4.5	ns	3-6	
t _w	MR Pulse Width HIGH or LOW	3.3 5.0	2.0 1.5	5.5 4.0	6.0 4.5	ns	3-6	
t _{rec}	Recovery Time MR to CP	3.3 5.0	1.5 1.0	3.5 2.0	4.5 3.0	ns	3-9	

*Voltage Range 3.3 V is 3.3 V ±0.3 V. Voltage Range 5.0 V is 5.0 V ±0.5 V.

MC74AC273, MC74ACT273

DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74ACT		74ACT		Unit	Conditions
			T _A = +25°C		T _A = -40°C to +85°C			
			Typ	Guaranteed Limits				
V _{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0		V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
V _{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8		V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
V _{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4		V	I _{OUT} = -50 μA
		4.5 5.5	- -	3.86 4.86	3.76 4.76		V	*V _{IN} = V _{IL} or V _{IH} I _{OH} -24 mA -24 mA
V _{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1		V	I _{OUT} = 50 μA
		4.5 5.5	- -	0.36 0.36	0.44 0.44		V	*V _{IN} = V _{IL} or V _{IH} 24 mA I _{OL} 24 mA
I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0		μA	V _I = V _{CC} , GND
ΔI _{CCT}	Additional Max. I _{CC} /Input	5.5	0.6	-	1.5		mA	V _I = V _{CC} - 2.1 V
I _{OLD} I _{OHD}	†Minimum Dynamic Output Current	5.5 5.5	- -	- -	75 -75		mA	V _{OLD} = 1.65 V Max V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80		μA	V _{IN} = V _{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V _{CC} * (V)	74ACT			74ACT		Unit	Figure No.
			T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF			
			Min	Typ	Max	Min	Max		
f _{max}	Maximum Clock Frequency	5.0	125	200	–	125	–	MHz	3–3
t _{PHL}	Propagation Delay Clock to Output	5.0	3.0	6.0	10	2.5	11.0	ns	3–6
t _{PLH}	Propagation Delay Clock to Output	5.0	3.0	6.5	11	2.5	12.0	ns	3–6
t _{PHL}	Propagation Delay $\overline{\text{MR}}$ to Output	5.0	3.0	7.0	11	2.5	11.5	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V _{CC} * (V)	74ACT		74ACT	Unit	Figure No.
			T _A = +25°C C _L = 50 pF		T _A = -40°C to +85°C C _L = 50 pF		
			Typ	Guaranteed Minimum			
t _s	Setup Time, HIGH or LOW – Data to CP	5.0	3.0	4.5	5.0	ns	3–9
t _h	Hold Time, HIGH or LOW – Data to CP	5.0	–2.5	2.0	2.0	ns	3–9
t _w	Clock Pulse Width – HIGH or LOW	5.0	2.5	4.0	4.5	ns	3–6
t _w	$\overline{\text{MR}}$ Pulse Width – HIGH or LOW	5.0	2.5	4.0	4.5	ns	3–6
t _{rec}	Recovery Time – $\overline{\text{MR}}$ to CP	5.0	–1.0	2.0	3.0	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = 5.0 V
C _{PD}	Power Dissipation Capacitance	50	pF	V _{CC} = 5.0 V

MC74AC273, MC74ACT273

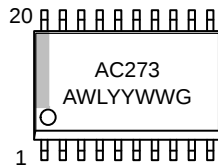
ORDERING INFORMATION

Device	Package	Shipping [†]
MC74AC273DWG	SOIC-20WB (Pb-Free)	38 Units / Rail
MC74AC273DWR2G	SOIC-20WB (Pb-Free)	1000 / Tape & Reel
MC74AC273DTR2G	TSSOP-20 (Pb-Free)	2500 / Tape & Reel
MC74ACT273DWG	SOIC-20WB (Pb-Free)	38 Units / Rail
MC74ACT273DWR2G	SOIC-20WB (Pb-Free)	1000 / Tape & Reel
MC74ACT273DTR2G	TSSOP-20 (Pb-Free)	2500 / Tape & Reel

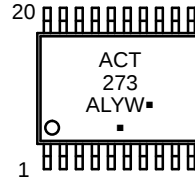
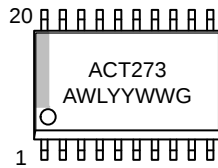
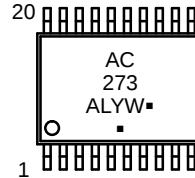
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MARKING DIAGRAMS

SOIC-20WB



TSSOP-20

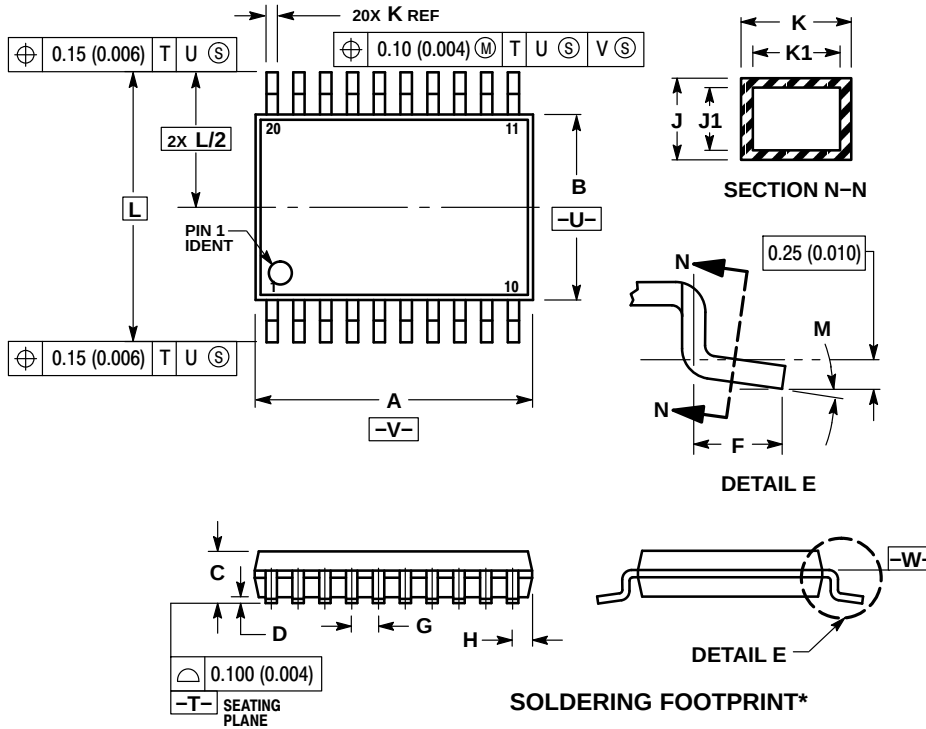


A = Assembly Location
 WL, L = Wafer Lot
 YY, Y = Year
 WW, W = Work Week
 G or ■ = Pb-Free Package
 (Note: Microdot may be in either location)

MC74AC273, MC74ACT273

PACKAGE DIMENSIONS

TSSOP-20
DT SUFFIX
CASE 948E-02
ISSUE C



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

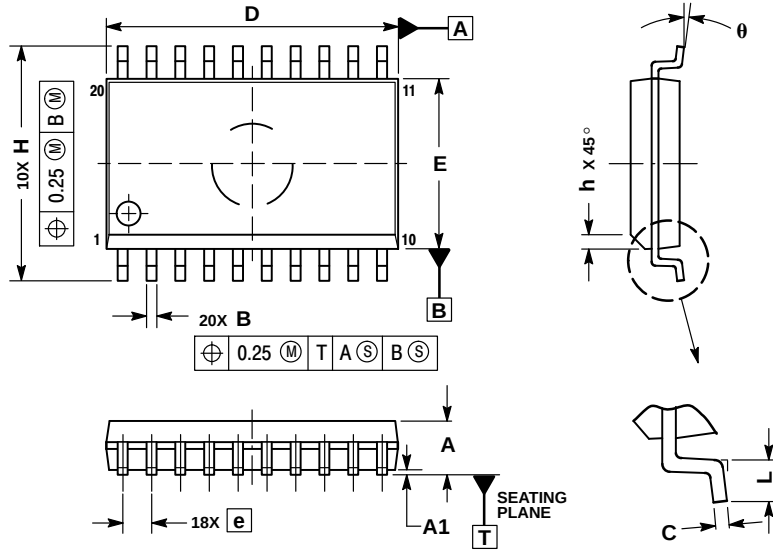
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74AC273, MC74ACT273

PACKAGE DIMENSIONS

SOIC-20W
DW SUFFIX
CASE 751D-05
ISSUE G



NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0°	7°

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marketing.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: <http://www.onsemi.com/orderlit>

For additional information, please contact your local Sales Representative